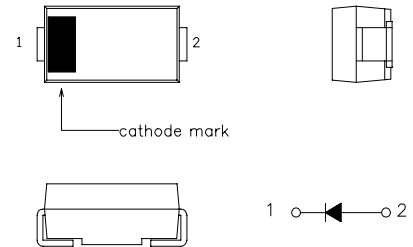


FRD Type : EC11FS2

FEATURES

- * Miniature Size, Surface Mount Device
- * Ultra-Fast Recovery
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

Rating	Symbol	EC11FS2			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	200			V
Non-repetitive Peak Reverse Voltage	V _{RSM}	220			V
Average Rectified Output Current	I _O	0.81	Ta=25°C *1	50Hz Half Sine Wave Resistive Load	A
		1.0	Ta=34°C *2		
RMS Forward Current	I _{F(RMS)}	1.57			A
Surge Forward Current	I _{FSM}	20	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	-40 to +150			°C
Storage Temperature Range	T _{stg}	-40 to +150			°C

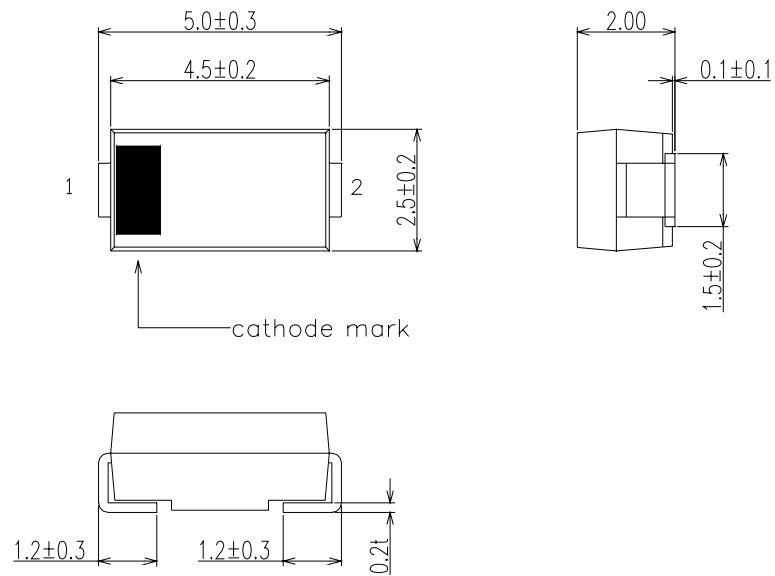
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	I_{RM}	$T_j = 25^{\circ}\text{C}$, $V_{RM} = V_{RRM}$	-	-	10	μA
Peak Forward Voltage	V_{FM}	$T_j = 25^{\circ}\text{C}$, $I_{FM} = 1.0\text{A}$	-	-	0.98	V
Reverse Recovery Time	t_{rr}	$I_{FM} = 1\text{A}$, $-di/dt = 50\text{A}/\mu\text{s}$, $T_a = 25^{\circ}\text{C}$	-	-	30	ns
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	157	$^{\circ}\text{C}/\text{W}$
			*2	-	108	

*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

EC11FS2 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

